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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

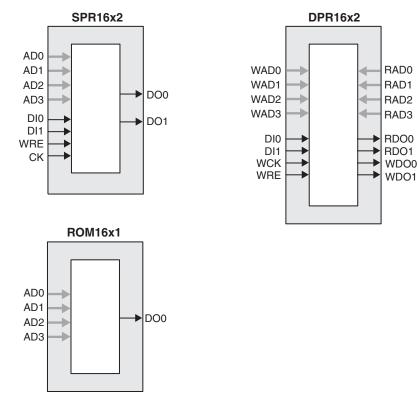
Details	
Product Status	Obsolete
Number of LABs/CLBs	32
Number of Logic Elements/Cells	256
Total RAM Bits	-
Number of I/O	78
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	100-LFBGA, CSPBGA
Supplier Device Package	100-CSBGA (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo256e-5m100c

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



Figure 2-6. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table	2-4.	PFU	Modes	of	Operation
-------	------	-----	-------	----	-----------

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x 2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

Routing

There are many resources provided in the MachXO devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.

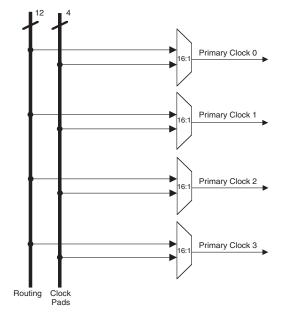


The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

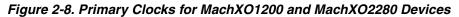
Clock/Control Distribution Network

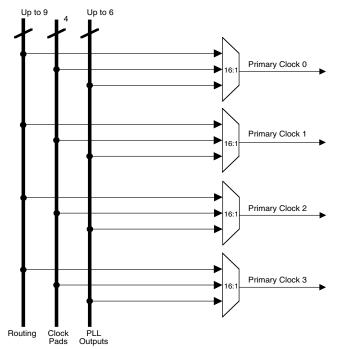
The MachXO family of devices provides global signals that are available to all PFUs. These signals consist of four primary clocks and four secondary clocks. Primary clock signals are generated from four 16:1 muxes as shown in Figure 2-7 and Figure 2-8. The available clock sources for the MachXO256 and MachXO640 devices are four dual function clock pins and 12 internal routing signals. The available clock sources for the MachXO2280 devices are four dual function clock pins, up to nine internal routing signals and up to six PLL outputs.

Figure 2-7. Primary Clocks for MachXO256 and MachXO640 Devices



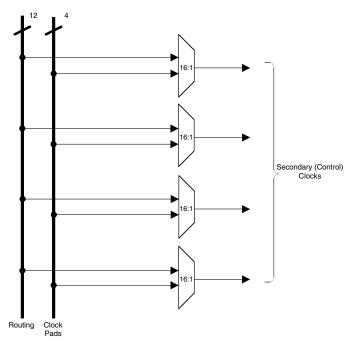






Four secondary clocks are generated from four 16:1 muxes as shown in Figure 2-9. Four of the secondary clock sources come from dual function clock pins and 12 come from internal routing.

Figure 2-9. Secondary Clocks for MachXO Devices





sysCLOCK Phase Locked Loops (PLLs)

The MachXO1200 and MachXO2280 provide PLL support. The source of the PLL input divider can come from an external pin or from internal routing. There are four sources of feedback signals to the feedback divider: from CLKINTFB (internal feedback port), from the global clock nets, from the output of the post scalar divider, and from the routing (or from an external pin). There is a PLL_LOCK signal to indicate that the PLL has locked on to the input clock signal. Figure 2-10 shows the sysCLOCK PLL diagram.

The setup and hold times of the device can be improved by programming a delay in the feedback or input path of the PLL which will advance or delay the output clock with reference to the input clock. This delay can be either programmed during configuration or can be adjusted dynamically. In dynamic mode, the PLL may lose lock after adjustment and not relock until the t_{LOCK} parameter has been satisfied. Additionally, the phase and duty cycle block allows the user to adjust the phase and duty cycle of the CLKOS output.

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider, post scalar divider, and secondary clock divider. The input clock divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal. The post scalar divider allows the VCO to operate at higher frequencies than the clock output, thereby increasing the frequency range. The secondary divider is used to derive lower frequency outputs.

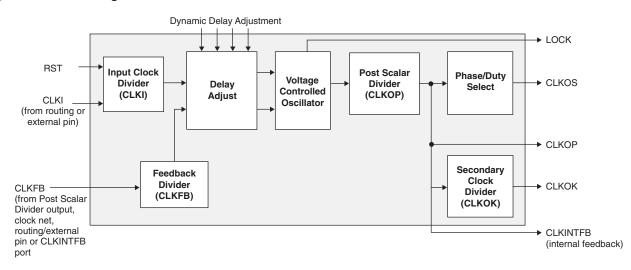
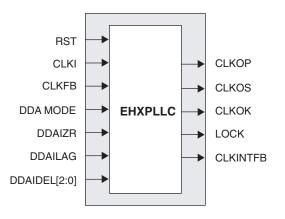


Figure 2-10. PLL Diagram

Figure 2-11 shows the available macros for the PLL. Table 2-5 provides signal description of the PLL Block.

Figure 2-11. PLL Primitive



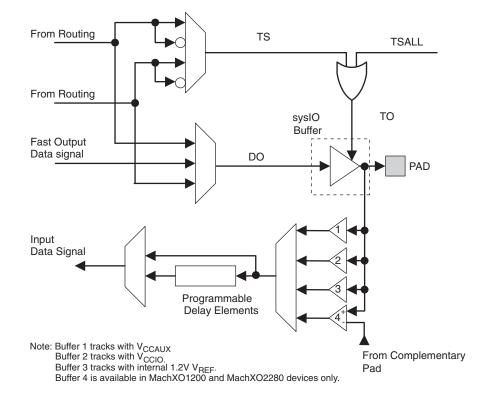


output data signals are multiplexed and provide a single signal to the I/O pin via the sysIO buffer. Figure 2-17 shows the MachXO PIO logic.

The tristate control signal is multiplexed from the output data signals and their complements. In addition a global signal (TSALL) from a dedicated pad can be used to tristate the sysIO buffer.

The PIO receives an input signal from the pin via the sysIO buffer and provides this signal to the core of the device. In addition there are programmable elements that can be utilized by the design tools to avoid positive hold times.

Figure 2-17. MachXO PIO Block Diagram



sysIO Buffer

Each I/O is associated with a flexible buffer referred to as a sysIO buffer. These buffers are arranged around the periphery of the device in groups referred to as Banks. The sysIO buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, TTL, BLVDS, LVDS and LVPECL.

In the MachXO devices, single-ended output buffers and ratioed input buffers (LVTTL, LVCMOS and PCI) are powered using V_{CCIO} . In addition to the Bank V_{CCIO} supplies, the MachXO devices have a V_{CC} core logic power supply, and a V_{CCAUX} supply that powers up a variety of internal circuits including all the differential and referenced input buffers.

MachXO256 and MachXO640 devices contain single-ended input buffers and single-ended output buffers with complementary outputs on all the I/O Banks.

MachXO1200 and MachXO2280 devices contain two types of sysIO buffer pairs.

1. Top and Bottom sysIO Buffer Pairs

The sysIO buffer pairs in the top and bottom Banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (for ratioed or absolute input levels). The I/O pairs on the top and bottom



the system. These capabilities make the MachXO ideal for many multiple power supply and hot-swap applications.

Sleep Mode

The MachXO "C" devices ($V_{CC} = 1.8/2.5/3.3V$) have a sleep mode that allows standby current to be reduced dramatically during periods of system inactivity. Entry and exit to Sleep mode is controlled by the SLEEPN pin.

During Sleep mode, the logic is non-operational, registers and EBR contents are not maintained, and I/Os are tristated. Do not enter Sleep mode during device programming or configuration operation. In Sleep mode, power supplies are in their normal operating range, eliminating the need for external switching of power supplies. Table 2-11 compares the characteristics of Normal, Off and Sleep modes.

Characteristic	Normal	Off	Sleep
SLEEPN Pin	High	—	Low
Static Icc	Typical <10mA	0	Typical <100uA
I/O Leakage	<10µA	<1mA	<10µA
Power Supplies VCC/VCCIO/VCCAUX	Normal Range	0	Normal Range
Logic Operation	User Defined	Non Operational	Non operational
I/O Operation	User Defined	Tri-state	Tri-state
JTAG and Programming circuitry	Operational	Non-operational	Non-operational
EBR Contents and Registers	Maintained	Non-maintained	Non-maintained

Table 2-11. Characteristics of Normal, Off and Sleep Modes

SLEEPN Pin Characteristics

The SLEEPN pin behaves as an LVCMOS input with the voltage standard appropriate to the VCC supply for the device. This pin also has a weak pull-up, along with a Schmidt trigger and glitch filter to prevent false triggering. An external pull-up to VCC is recommended when Sleep Mode is not used to ensure the device stays in normal operation mode. Typically, the device enters sleep mode several hundred nanoseconds after SLEEPN is held at a valid low and restarts normal operation as specified in the Sleep Mode Timing table. The AC and DC specifications portion of this data sheet shows a detailed timing diagram.

Oscillator

Every MachXO device has an internal CMOS oscillator. The oscillator can be routed as an input clock to the clock tree or to general routing resources. The oscillator frequency can be divided by internal logic. There is a dedicated programming bit to enable/disable the oscillator. The oscillator frequency ranges from 18MHz to 26MHz.

Configuration and Testing

The following section describes the configuration and testing features of the MachXO family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All MachXO devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port shares its power supply with one of the VCCIO Banks (MachXO256: V_{CCIO1} ; MachXO640: V_{CCIO2} ; MachXO1200 and MachXO2280: V_{CCIO5}) and can operate with LVCMOS3.3, 2.5, 1.8, 1.5, and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.



Supply Current (Sleep Mode)^{1, 2}

Symbol	Parameter	Device	Typ. ³	Max.	Units
		LCMXO256C	12	25	μA
	Core Dower Supply	LCMXO640C	12	25	μA
ICC	Core Power Supply	LCMXO1200C	12	25	μA
		LCMXO2280C	12	25	μA
		LCMXO256C	1	15	μA
L	Auxiliary Power Supply	LCMXO640C	1	25	μA
ICCAUX	Auxiliary Fower Supply	LCMXO1200C	1	45	μA
		LCMXO2280C	1	85	μA
I _{CCIO}	Bank Power Supply ⁴	All LCMXO 'C' Devices	2	30	μA

1. Assumes all inputs are configured as LVCMOS and held at the VCCIO or GND.

2. Frequency = 0MHz.

3. $T_A = 25^{\circ}C$, power supplies at nominal voltage.

4. Per Bank.

Supply Current (Standby)^{1, 2, 3, 4}

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.⁵	Units
		LCMXO256C	7	mA
		LCMXO640C	9	mA
I _{CC} Core Power Supply I _{CCAUX} Auxiliary Power Supply V _{CCAUX} = 3.3V		LCMXO1200C	14	mA
		LCMXO256C 7 LCMXO640C 9	mA	
CC	Core Power Supply	LCMXO256E	4	mA
5 OUET		LCMXO640E	6	mA
		LCMXO1200E	256C 7 640C 9 1200C 14 2280C 20 256E 4 640E 6 1200E 10 2280E 12 256E/C 5 640E/C 7 1200E/C 12 2280E/C 13	mA
		LCMXO2280E	12	mA
		LCMXO256E/C	5	mA
		LCMXO640E/C	7	mA
CCAUX	$V_{CCAUX} = 3.3V$	LCMXO1200E/C	12	mA
		LCMXO2280E/C	9 14 20 4 6 10 12 5 7 2 2 12 2 13	mA
ccio	Bank Power Supply ⁶	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.

2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at V_{CCIO} or GND.

3. Frequency = 0MHz.

4. User pattern = blank.

5. $T_J = 25^{\circ}C$, power supplies at nominal voltage.

6. Per Bank. $V_{CCIO} = 2.5V$. Does not include pull-up/pull-down.



sysIO Recommended Operating Conditions

		V _{CCIO} (V)	
Standard	Min.	Тур.	Max.
LVCMOS 3.3	3.135	3.3	3.465
LVCMOS 2.5	2.375	2.5	2.625
LVCMOS 1.8	1.71	1.8	1.89
LVCMOS 1.5	1.425	1.5	1.575
LVCMOS 1.2	1.14	1.2	1.26
LVTTL	3.135	3.3	3.465
PCI ³	3.135	3.3	3.465
LVDS ^{1, 2}	2.375	2.5	2.625
LVPECL ¹	3.135	3.3	3.465
BLVDS ¹	2.375	2.5	2.625
RSDS ¹	2.375	2.5	2.625

1. Inputs on chip. Outputs are implemented with the addition of external resistors.

2. MachXO1200 and MachXO2280 devices have dedicated LVDS buffers

3. Input on the top bank of the MachXO1200 and MachXO2280 only.

sysIO Single-Ended DC Electrical Characteristics

Input/Output		V _{IL}	V _{IH}		V _{OL} Max.	V _{OH} Min.		I _{OH} ¹
Standard	Min. (V)	Max. (V)	Min. (V)	Max. (V)	(V)	(V)	(mĀ)	(mÅ)
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	V _{CCIO} - 0.4	16, 12, 8, 4	-14, -12, -8, -4
	-0.5	0.0	2.0	5.0	0.2	V _{CCIO} - 0.2	0.1	-0.1
					0.4	2.4	16	-16
LVTTL	-0.3	0.8	2.0	3.6	0.4	V _{CCIO} - 0.4	12, 8, 4	-12, -8, -4
					0.2	V _{CCIO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V _{CCIO} - 0.4	16, 12, 8, 4	-14, -12, -8, -4
2000002.5	-0.5	0.7	1.7	0.0	0.2	V _{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.8	-0.3	0.35V _{CCIO}	0.65V _{CCIO}	3.6	0.4	V _{CCIO} - 0.4	16, 12, 8, 4	-14, -12, -8, -4
	-0.5	0.00 4 CCIO	0.00 4 CCIO	0.0	0.2	V _{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.5	-0.3	0.35V _{CCIO}	0.65V _{CCIO}	3.6	0.4	V _{CCIO} - 0.4	8, 4	-8, -4
2001000 1.5	-0.5	0.00 4 CCIO	0.00 4 CCIO	0.0	0.2	V _{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2	-0.3	0.42	0.78	3.6	0.4	V _{CCIO} - 0.4	6, 2	-6, -2
("C" Version)	-0.5	0.42	0.70	0.0	0.2	V _{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2	-0.3	0.35V _{CC}	0.65V _{CC}	3.6	0.4	V _{CCIO} - 0.4	6, 2	-6, -2
("E" Version)	-0.5	0.00 v CC	0.03 v CC	5.0	0.2	V _{CCIO} - 0.2	0.1	-0.1
PCI	-0.3	0.3V _{CCIO}	0.5V _{CCIO}	3.6	0.1V _{CCIO}	0.9V _{CCIO}	1.5	-0.5

 The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O Bank and the end of an I/O Bank, as shown in the logic signal connections table shall not exceed n * 8mA. Where n is the number of I/Os between Bank GND connections or between the last GND in a Bank and the end of a Bank.



Table 3-2. BLVDS DC Conditions¹

		Nominal		
Symbol	Description	Zo = 45	Zo = 90	Units
Z _{OUT}	Output impedance	100	100	Ohms
R _{TLEFT}	Left end termination	45	90	Ohms
R _{TRIGHT}	Right end termination	45	90	Ohms
V _{OH}	Output high voltage	1.375	1.48	V
V _{OL}	Output low voltage	1.125	1.02	V
V _{OD}	Output differential voltage	0.25	0.46	V
V _{CM}	Output common mode voltage	1.25	1.25	V
IDC	DC output current	11.2	10.2	mA

Over Recommended Operating Conditions

1. For input buffer, see LVDS table.

LVPECL

The MachXO family supports the differential LVPECL standard through emulation. This output standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs on all the devices. The LVPECL input standard is supported by the LVDS differential input buffer on certain devices. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL

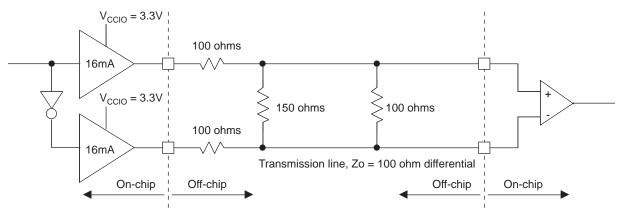


Table 3-3. LVPECL DC Conditions¹

Over	Recommended	Operating	Conditions
0101	11000011111011404	oporating	00110110110

Symbol	Description	Nominal	Units
Z _{OUT}	Output impedance	100	Ohms
R _P	Driver parallel resistor	150	Ohms
R _T	Receiver termination	100	Ohms
V _{OH}	Output high voltage	2.03	V
V _{OL}	Output low voltage	1.27	V
V _{OD}	Output differential voltage	0.76	V
V _{CM}	Output common mode voltage	1.65	V
Z _{BACK}	Back impedance	85.7	Ohms
I _{DC}	DC output current	12.7	mA

1. For input buffer, see LVDS table.



sysCLOCK PLL Timing

Over Recommended Operating Conditions

Parameter	Descriptions	Conditions	Min.	Max.	Units
			25	420	MHz
f _{IN}	Input Clock Frequency (CLKI, CLKFB)	Input Divider (M) = 1; Feedback Divider (N) $\leq 4^{5, 6}$	18	25	MHz
f _{OUT}	Output Clock Frequency (CLKOP, CLKOS)		25	420	MHz
f _{OUT2}	K-Divider Output Frequency (CLKOK)		0.195	210	MHz
f _{VCO}	PLL VCO Frequency		420	840	MHz
			25	—	MHz
f _{PFD}	Phase Detector Input Frequency	Input Divider (M) = 1; Feedback Divider (N) $\leq 4^{5, 6}$	18	25	MHz
AC Characte	eristics			•	•
t _{DT}	Output Clock Duty Cycle	Default duty cycle selected ³	45	55	%
t_{PH}^{4}	Output Phase Accuracy		—	0.05	UI
t 1	Output Clock Period Jitter	f _{OUT} >= 100 MHz	—	+/-120	ps
t _{OPJIT} 1		f _{OUT} < 100 MHz	—	0.02	UIPP
t _{SK}	Input Clock to Output Clock Skew	Divider ratio = integer	—	+/-200	ps
t _W	Output Clock Pulse Width	At 90% or 10% ³	1	—	ns
t _{LOCK} ²	PLL Lock-in Time		—	150	μs
t _{PA}	Programmable Delay Unit		100	450	ps
+	Input Clock Period Jitter	$f_{OUT} \ge 100 \text{ MHz}$	—	+/-200	ps
t _{IPJIT}		f _{OUT} < 100 MHz	—	0.02	UI
t _{FBKDLY}	External Feedback Delay		_	10	ns
t _{HI}	Input Clock High Time	90% to 90%	0.5	_	ns
t _{LO}	Input Clock Low Time	10% to 10%	0.5	_	ns
t _{RST}	RST Pulse Width		10	—	ns

1. Jitter sample is taken over 10,000 samples of the primary PLL output with a clean reference clock.

2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.

3. Using LVDS output buffers.

4. CLKOS as compared to CLKOP output.

5. When using an input frequency less than 25 MHz the output frequency must be less than or equal to 4 times the input frequency.

6. The on-chip oscillator can be used to provide reference clock input to the PLL provided the output frequency restriction for clock inputs below 25 MHz are followed.

Rev. A 0.19



MachXO Family Data Sheet Pinout Information

June 2013

Data Sheet DS1002

Signal Descriptions

Signal Name	I/O	Descriptions
General Purpose		
		[Edge] indicates the edge of the device on which the pad is located. Valid edge designa- tions are L (Left), B (Bottom), R (Right), T (Top).
		[Row/Column Number] indicates the PFU row or the column of the device on which the PIO Group exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number.
P[Edge] [Row/Column	I/O	[A/B/C/D/E/F] indicates the PIO within the group to which the pad is connected.
Number]_[A/B/C/D/E/F]		Some of these user programmable pins are shared with special function pins. When not used as special function pins, these pins can be programmed as I/Os for user logic.
		During configuration of the user-programmable I/Os, the user has an option to tri-state the I/Os and enable an internal pull-up resistor. This option also applies to unused pins (or those not bonded to a package pin). The default during configuration is for user-programmable I/Os to be tri-stated with an internal pull-up resistor enabled. When the device is erased, I/Os will be tri-stated with an internal pull-up resistor enabled.
GSRN	I	Global RESET signal (active low). Dedicated pad, when not in use it can be used as an I/O pin.
TSALL	I	TSALL is a dedicated pad for the global output enable signal. When TSALL is high all the outputs are tristated. It is a dual function pin. When not in use, it can be used as an I/O pin.
NC	—	No connect.
GND	—	GND - Ground. Dedicated pins.
V _{CC}	—	VCC - The power supply pins for core logic. Dedicated pins.
V _{CCAUX}	_	VCCAUX - the Auxiliary power supply pin. This pin powers up a variety of internal circuits including all the differential and referenced input buffers. Dedicated pins.
V _{CCIOx}	—	V _{CCIO} - The power supply pins for I/O Bank x. Dedicated pins.
SLEEPN ¹	I	Sleep Mode pin - Active low sleep pin.b When this pin is held high, the device operates normally.b This pin has a weak internal pull-up, but when unused, an external pull-up to V_{CC} is recommended. When driven low, the device moves into Sleep mode after a specified time.
PLL and Clock Functions	(Used a	as user programmable I/O pins when not used for PLL or clock pins)
[LOC][0]_PLL[T, C]_IN	_	Reference clock (PLL) input Pads: [LOC] indicates location. Valid designations are ULM (Upper PLL) and LLM (Lower PLL). $T = true$ and $C = complement$.
[LOC][0]_PLL[T, C]_FB		Optional feedback (PLL) input Pads: [LOC] indicates location. Valid designations are ULM (Upper PLL) and LLM (Lower PLL). T = true and C = complement.
PCLK [n]_[1:0]	—	Primary Clock Pads, n per side.
Test and Programming (De	dicate	d pins)
TMS	Ι	Test Mode Select input pin, used to control the 1149.1 state machine.
ТСК	Ι	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data input pin, used to load data into the device using an 1149.1 state machine.
TDO	0	Output pin -Test Data output pin used to shift data out of the device using 1149.1.
1 Applies to MachXO "C" devic		

1. Applies to MachXO "C" devices only. NC for "E" devices.

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Pin Information Summary

		LCMXC	0256C/E			LCMXO640C/E		
Pin Type		100 TQFP	100 csBGA	100 TQFP	144 TQFP	100 csBGA	132 csBGA	256 caBGA / 256 ftBGA
Single Ended User I/O		78	78	74	113	74	101	159
Differential Pair User I/O1		38	38	17	43	17	42	79
Muxed		6	6	6	6	6	6	6
TAP		4	4	4	4	4	4	4
Dedicated (Total Without Supp	olies)	5	5	5	5	5	5	5
VCC		2	2	2	4	2	4	4
VCCAUX		1	1	1	2	1	2	2
	Bank0	3	3	2	2	2	2	4
VOOIO	Bank1	3	3	2	2	2	2	4
VCCIO	Bank2	—	—	2	2	2	2	4
	Bank3	—	—	2	2	2	2	4
GND		8	8	10	12	10	12	18
NC		0	0	0	0	0	0	52
	Bank0	41/20	41/20	18/5	29/10	18/5	26/11	42/21
Single Ended/Differential I/O	Bank1	37/18	37/18	21/4	30/11	21/4	27/12	40/20
per Bank	Bank2	_	—	14/2	24/9	14/2	21/9	36/18
	Bank3	_	_	21/6	30/13	21/6	27/10	40/20

1. These devices support emulated LVDS outputs.pLVDS inputs are not supported.

			LCMXO	1200C/E			l	CMXO2280C/	/E	
Pin Type		100 TQFP	144 TQFP	132 csBGA	256 caBGA / 256 ftBGA	100 TQFP	144 TQFP	132 csBGA	256 caBGA / 256 ftBGA	324 ftBGA
Single Ended User I/O		73	113	101	211	73	113	101	211	271
Differential Pair User I/O1		27	48	42	105	30	47	41	105	134
Muxed		6	6	6	6	6	6	6	6	6
TAP		4	4	4	4	4	4	4	4	4
Dedicated (Total Without Supplies)		5	5	5	5	5	5	5	5	5
VCC		4	4	4	4	2	4	4	4	6
VCCAUX		2	2	2	2	2	2	2	2	2
	Bank0	1	1	1	2	1	1	1	2	2
	Bank1	1	1	1	2	1	1	1	2	2
	Bank2	1	1	1	2	1	1	1	2	2
VCCIO	Bank3	1	1	1	2	1	1	1	2	2
VCCIO	Bank4	1	1	1	2	1	1	1	2	2
	Bank5	1	1	1	2	1	1	1	2	2
	Bank6	1	1	1	2	1	1	1	2	2
	Bank7	1	1	1	2	1	1	1	2	2
GND	•	8	12	12	18	8	12	12	18	24
NC		0	0	0	0	0	0	0	0	0
	Bank0	10/3	14/6	13/5	26/13	9/3	13/6	12/5	24/12	34/17
	Bank1	8/2	15/7	13/5	28/14	9/3	16/7	14/5	30/15	36/18
	Bank2	10/4	15/7	13/6	26/13	10/4	15/7	13/6	26/13	34/17
Single Ended/Differential I/O	Bank3	11/5	15/7	14/7	28/14	11/5	15/7	14/7	28/14	34/17
per Bank	Bank4	8/3	14/5	13/5	27/13	8/3	14/4	13/4	29/14	35/17
	Bank5	5/2	10/4	8/2	22/11	5/2	10/4	8/2	20/10	30/15
	Bank6	10/3	15/6	13/6	28/14	10/4	15/6	13/6	28/14	34/17
	Bank7	11/5	15/6	14/6	26/13	11/5	15/6	14/6	26/13	34/17

1. These devices support on-chip LVDS buffers for left and right I/O Banks.



Power Supply and NC

Signal	100 TQFP ¹	144 TQFP ¹	100 csBGA ²
VCC	LCMXO256/640: 35, 90 LCMXO1200/2280: 17, 35, 66, 91	21, 52, 93, 129	P7, B6
VCCIO0	LCMXO256: 60, 74, 92 LCMXO640: 80, 92 LCMXO1200/2280: 94	LCMXO640: 117, 135 LCMXO1200/2280: 135	LCMXO256: H14, A14, B5 LCMXO640: B12, B5
VCCIO1	LCMXO256: 10, 24, 41 LCMXO640: 60, 74 LCMXO1200/2280: 80	LCMXO640: 82, 98 LCMXO1200/2280: 117	LCMXO256: G1, P1, P10 LCMXO640: H14, A14
VCCIO2	LCMXO256: None LCMXO640: 29, 41 LCMXO1200/2280: 70	LCMXO640: 38, 63 LCMXO1200/2280: 98	LCMXO256: None LCMXO640: P4, P10
VCCIO3	LCMXO256: None LCMXO640: 10, 24 LCMXO1200/2280: 56	LCMXO640: 10, 26 LCMXO1200/2280: 82	LCMXO256: None LCMXO640: G1, P1
VCCIO4	LCMXO256/640: None LCMXO1200/2280: 44	LCMXO640: None LCMXO1200/2280: 63	-
VCCIO5	LCMXO256/640: None LCMXO1200/2280: 27	LCMXO640: None LCMXO1200/2280: 38	—
VCCIO6	LCMXO256/640: None LCMXO1200/2280: 20	LCMXO640: None LCMXO1200/2280: 26	—
VCCIO7	LCMXO256/640: None LCMXO1200/2280: 6	LCMXO640: None LCMXO1200/2280: 10	—
VCCAUX	LCMXO256/640: 88 LCMXO1200/2280: 36, 90	53, 128	B7
GND ³	LCMXO256: 40, 84, 62, 75, 93, 12, 25, 42 LCMXO640: 40, 84, 81, 93, 62, 75, 30, 42, 12, 25 LCMXO1200/2280: 9, 41, 59, 83, 100, 76, 50, 26	16, 59, 88, 123, 118, 136, 83, 99, 37, 64, 11, 27	LCMXO256: N9, B9, G14, B13, A4, H1, N2, N10 LCMXO640: N9, B9, A10, A4, G14, B13, N3, N10, H1, N2
NC ⁴			—

1. Pin orientation follows the conventional order from pin 1 marking of the top side view and counter-clockwise.

Pin orientation follows the contention of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
All grounds must be electrically connected at the board level. For fpBGA and ftBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
NC pins should not be connected to any active signals, VCC or GND.



LCMXO256 and LCMXO640 Logic Signal Connections: 100 csBGA

		LCMXO25	6		LCMXO640						
Ball Number	Ball Function	Bank	Dual Function	Differen- tial	Ball Number	Ball Function	Bank	Dual Function	Differen- tial		
B1	PL2A	1		Т	B1	PL2A	3		Т		
C1	PL2B	1		С	C1	PL2C	3		Т		
D2	PL3A	1		Т	D2	PL2B	3		С		
D1	PL3B	1		С	D1	PL2D	3		С		
C2	PL3C	1		Т	C2	PL3A	3		Т		
E1	PL3D	1		С	E1	PL3B	3		С		
E2	PL4A	1		Т	E2	PL3C	3		Т		
F1	PL4B	1		С	F1	PL3D	3		С		
F2	PL5A	1		Т	F2	PL4A	3				
G2	PL5B	1		С	G2	PL4C	3		Т		
H1	GNDIO1	1			H1	GNDIO3	3				
H2	PL5C	1		Т	H2	PL4D	3		С		
J1	PL5D	1	GSRN	С	J1	PL5B	3	GSRN			
J2	PL6A	1		Т	J2	PL7B	3				
K1	PL6B	1	TSALL	С	K1	PL8C	3	TSALL	Т		
K2	PL7A	1		Т	K2	PL8D	3		С		
L1	PL7B	1		С	L1	PL9A	3				
L2	PL7C	1		Т	L2	PL9C	3				
M1	PL7D	1		С	M1	PL10A	3				
M2	PL8A	1		Т	M2	PL10C	3				
N1	PL8B	1		С	N1	PL11A	3				
M3	PL9A	1		Т	M3	PL11C	3				
N2	GNDIO1	1			N2	GNDIO3	3				
P2	TMS	1	TMS		P2	TMS	2	TMS			
P3	PL9B	1		С	P3	PB2C	2				
N4	TCK	1	ТСК		N4	ТСК	2	ТСК			
P4	PB2A	1		Т	P4	VCCIO2	2				
N3	PB2B	1		С	N3	GNDIO2	2				
P5	TDO	1	TDO		P5	TDO	2	TDO			
N5	PB2C	1		Т	N5	PB4C	2				
P6	TDI	1	TDI		P6	TDI	2	TDI			
N6	PB2D	1		С	N6	PB4E	2				
P7	VCC	-			P7	VCC	-				
N7	PB3A	1	PCLK1_1**	Т	N7	PB5B	2	PCLK2_1**			
P8	PB3B	1		С	P8	PB5D	2				
N8	PB3C	1	PCLK1_0**	Т	N8	PB6B	2	PCLK2_0**			
P9	PB3D	1		С	P9	PB6C	2				
N10	GNDIO1	1		-	N10	GNDIO2	2				
P11	PB4A	1		Т	P11	PB8B	2				
N11	PB4B	1		C	N11	PB8C	2		Т		
P12	PB4C	1		T	P12	PB8D	2		C		
N12	PB4D	1		C	N12	PB9A	2	+	•		



LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 144 TQFP (Cont.)

		L	CMXO640				LCMXO1200				LCMXO2280	
Pin Number	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
101	PR3D	1		С	PR4B	2		C*	PR5B	2		C*
102	PR3C	1		Т	PR4A	2		T*	PR5A	2		T*
103	PR3B	1		С	PR3D	2		С	PR4D	2		С
104	PR2D	1		С	PR3C	2		Т	PR4C	2		Т
105	PR3A	1		Т	PR3B	2		C*	PR4B	2		C*
106	PR2B	1		С	PR3A	2		T*	PR4A	2		T*
107	PR2C	1		Т	PR2B	2		С	PR3B	2		C*
108	PR2A	1		Т	PR2A	2		Т	PR3A	2		T*
109	PT9F	0		С	PT11D	1		С	PT16D	1		С
110	PT9D	0		С	PT11C	1		Т	PT16C	1		Т
111	PT9E	0		Т	PT11B	1		С	PT16B	1		С
112	PT9B	0		С	PT11A	1		Т	PT16A	1		Т
113	PT9C	0		Т	PT10F	1		С	PT15D	1		С
114	PT9A	0		Т	PT10E	1		Т	PT15C	1		Т
115	PT8C	0			PT10D	1		С	PT14B	1		С
116	PT8B	0		С	PT10C	1		Т	PT14A	1		Т
117	VCCIO0	0			VCCIO1	1			VCCIO1	1		
118	GNDIO0	0			GNDIO1	1			GNDIO1	1		
119	PT8A	0		Т	PT9F	1		С	PT12F	1		С
120	PT7E	0			PT9E	1		Т	PT12E	1		Т
121	PT7C	0			PT9B	1		С	PT12D	1		С
122	PT7A	0			PT9A	1		Т	PT12C	1		Т
123	GND	-			GND	-			GND	-		
124	PT6B	0	PCLK0_1***	С	PT7D	1	PCLK1_1***		PT10B	1	PCLK1_1***	
125	PT6A	0		Т	PT7B	1		С	PT9D	1		С
126	PT5C	0			PT7A	1		Т	PT9C	1		Т
127	PT5B	0	PCLK0_0***		PT6F	0	PCLK1_0***		PT9B	1	PCLK1_0***	
128	VCCAUX	-			VCCAUX	-			VCCAUX	-		
129	VCC	-			VCC	-			VCC	-		
130	PT4D	0			PT5D	0		С	PT7B	0		С
131	PT4B	0		С	PT5C	0		Т	PT7A	0		Т
132	PT4A	0		Т	PT5B	0		С	PT6D	0		
133	PT3F	0			PT5A	0		Т	PT6E	0		Т
134	PT3D	0			PT4B	0			PT6F	0		С
135	VCCIO0	0			VCCIO0	0			VCCIO0	0	-	
136	GNDIO0	0			GNDIO0	0			GNDIO0	0	-	
137	PT3B	0		С	PT3D	0		С	PT4B	0		Т
138	PT2F	0		С	PT3C	0		Т	PT4A	0		С
139	PT3A	0		Т	PT3B	0		С	PT3B	0		С
140	PT2D	0		С	PT3A	0		Т	PT3A	0		Т
141	PT2E	0		Т	PT2D	0		С	PT2D	0		С
142	PT2B	0		С	PT2C	0		Т	PT2C	0		Т
143	PT2C	0		Т	PT2B	0		С	PT2B	0		С
144	PT2A	0		Т	PT2A	0		Т	PT2A	0		Т

*Supports true LVDS outputs.

**NC for "E" devices.

***Primary clock inputs arer single-ended.



LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 256 caBGA / 256 ftBGA (Cont.)

		LCM)	KO640				LCN	IXO1200				LCN	IXO2280	
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball	Ball	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
J13	PR8C	1	Tunction	T	J13	PR11A	3	runction	T*	J13	PR14A	3	Tunction	T*
GND	GND	-			GND	GND	-			GND	GND	-		
K14	PR8B	1		с	K14	PR10D	3		С	K14	PR13D	3		с
J14	PR8A	1		T	J14	PR10C	3		T	J14	PR13C	3		T
K15	PR7D	1		C	K15	PR10B	3		C*	K15	PR13B	3		C*
J15	PR7C	1		T	J15	PR10A	3		T*	J15	PR13A	3		T*
-	-	-			GND	GNDIO3	3		-	GND	GNDIO3	3		-
-	-				VCCIO3	VCCIO3	3			VCCIO3	VCCIO3	3		
K12	NC				K12	PR9D	3		С	K12	PR11D	3		С
J12	NC				J12	PR9C	3		Т	J12	PR11C	3		Т
J16	PR7B	1		С	J16	PR9B	3		C*	J16	PR11B	3		C*
H16	PR7A	1		Т	H16	PR9A	3		T*	H16	PR11A	3		T*
H15	PR6B	1		С	H15	PR8D	2		С	H15	PR10D	2		С
G15	PR6A	1		Т	G15	PR8C	2		т	G15	PR10C	2		т
H14	PR5D	1		С	H14	PR8B	2		C*	H14	PR10B	2		C*
G14	PR5C	1		Т	G14	PR8A	2		T*	G14	PR10A	2		T*
GND	GNDIO1	1			GND	GNDIO2	2			GND	GNDIO2	2		
VCCIO1	VCCIO1	1			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		
H13	PR6D	1		С	H13	PR7D	2		С	H13	PR9D	2		С
H12	PR6C	1		Т	H12	PR7C	2		Т	H12	PR9C	2		Т
G13	PR4D	1		С	G13	PR7B	2		C*	G13	PR9B	2		C*
G12	PR4C	1		Т	G12	PR7A	2		T*	G12	PR9A	2		T*
G16	PR5B	1		С	G16	PR6D	2		С	G16	PR7D	2		С
F16	PR5A	1		Т	F16	PR6C	2		Т	F16	PR7C	2		Т
F15	PR4B	1		С	F15	PR6B	2		C*	F15	PR7B	2		C*
E15	PR4A	1		Т	E15	PR6A	2		T*	E15	PR7A	2		T*
E16	PR3B	1		С	E16	PR5D	2		С	E16	PR6D	2		С
D16	PR3A	1		Т	D16	PR5C	2		Т	D16	PR6C	2		Т
VCCIO1	VCCIO1	1			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		
GND	GNDIO1	1			GND	GNDIO2	2			GND	GNDIO2	2		
D15	PR2D	1		С	D15	PR5B	2		C*	D15	PR6B	2		C*
C15	PR2C	1		Т	C15	PR5A	2		T*	C15	PR6A	2		T*
C16	PR2B	1		С	C16	PR4D	2		С	C16	PR5D	2		С
B16	PR2A	1		Т	B16	PR4C	2		Т	B16	PR5C	2		Т
F14	PR3D	1		С	F14	PR4B	2		C*	F14	PR5B	2		C*
E14	PR3C	1		Т	E14	PR4A	2		T*	E14	PR5A	2		T*
-	-	-			-	-	-			GND	GND	-		
F12	NC				F12	PR3D	2		С	F12	PR4D	2		С
F13	NC				F13	PR3C	2		T	F13	PR4C	2		T
E12	NC				E12	PR3B	2		C*	E12	PR4B	2		C*
E13	NC				E13	PR3A	2		T*	E13	PR4A	2		T*
D13	NC				D13	PR2B	2		C T	D13	PR3B	2		C*
D14	NC				D14	PR2A	2		Т	D14	PR3A	2		T*
VCCIO0	VCCIO0	0			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		<u> </u>
GND	GNDIO0	0			GND	GNDIO2	2			GND	GNDIO2	2 1		ł
GND	GNDIO0	0			GND	GNDIO1				GND	GNDIO1			
VCCIO0 B15	VCCIO0 NC	0			VCCIO1 B15	VCCIO1 PT11D	1		с	VCCIO1 B15	VCCIO1 PT16D	1		С
A15	NC				A15	PT11D PT11C	1		Т	A15	PT16D PT16C	1		т
C14	NC				C14	PT11B	1		C	C14	PT16C PT16B	1		C
B14	NC				B14	PT11B PT11A	1		Т	B14	PT16B PT16A	1		Т
C13	PT9F	0		С	C13	PT10F	1		C	C13	PT16A PT15D	1		C
B13	PT9E	0		т	B13	PT10F	1		т	B13	PT15D	1		т
013	LISE	U		1	013	FIIVE	L '			013	F1130	· ·		I



LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

Dell Number		LCMXO2280	Dual Free stires	D:#*****
Ball Number	Ball Function	Bank	Dual Function	Differentia
V10	PB9B	4		С
N10	PB9C	4		Т
R10	PB9D	4		С
P10	PB10F	4	PCLK4_1***	С
T10	PB10E	4		Т
U10	PB10D	4		С
V11	PB10C	4		Т
U11	PB10B	4	PCLK4_0***	С
VCCIO4	VCCIO4	4		
GND	GNDIO4	4		
T11	PB10A	4		Т
U12	PB11A	4		Т
R11	PB11B	4		С
GND	GND	-		
T12	PB11C	4		Т
P11	PB11D	4		С
V12	PB12A	4		Т
V13	PB12B	4		С
R12	PB12C	4		Т
N11	PB12D	4		С
U13	PB12E	4		Т
VCCIO4	VCCIO4	4		
GND	GNDIO4	4		
V14	PB12F	4		С
T13	PB13A	4		Т
P12	PB13B	4		С
R13	PB13C	4		Т
N12	PB13D	4		С
V15	PB14A	4		Т
U14	PB14B	4		С
V16	PB14C	4		Т
GND	GND	-		
T14	PB14D	4		С
U15	PB15A	4		Т
V17	PB15B	4		С
P13**	SLEEPN	-	SLEEPN	
T15	PB15D	4		
U16	PB16A	4		Т
V18	PB16B	4		C
N13	PB16C	4		T
R14	PB16D	4		C
VCCIO4	VCCIO4	4		-
GND	GNDIO4	4		



LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

		LCMXO2280		B 1/2
Ball Number	Ball Function	Bank	Dual Function	Differential
J13	PR10C	2		Т
M18	PR10B	2		C*
L18	PR10A	2		T*
GND	GNDIO2	2		
VCCIO2	VCCIO2	2		
H16	PR9D	2		С
H14	PR9C	2		Т
K18	PR9B	2		C*
J18	PR9A	2		T*
J17	PR8D	2		С
VCC	VCC	-		
H18	PR8C	2		Т
H17	PR8B	2		C*
G17	PR8A	2		Τ*
H13	PR7D	2		С
H15	PR7C	2		Т
G18	PR7B	2		C*
F18	PR7A	2		T*
G14	PR6D	2		С
G16	PR6C	2		Т
VCCIO2	VCCIO2	2		
GND	GNDIO2	2		
E18	PR6B	2		C*
F17	PR6A	2		T*
G13	PR5D	2		С
G15	PR5C	2		Т
E17	PR5B	2		C*
E16	PR5A	2		T*
GND	GND	-		
F15	PR4D	2		С
E15	PR4C	2		Т
D17	PR4B	2		C*
D18	PR4A	2		T*
B18	PR3D	2		С
C18	PR3C	2		Т
C16	PR3B	2		C*
D16	PR3A	2		T*
C17	PR2B	2		С
D15	PR2A	2		Т
VCCIO2	VCCIO2	2		
GND	GNDIO2	2		
GND	GNDIO1	1		
VCCIO1	VCCIO1	1		



LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

		LCMXO2280		
Ball Number	Ball Function	Bank	Dual Function	Differential
A10	PT8E	0		Т
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
A9	PT8D	0		С
C9	PT8C	0		Т
B9	PT8B	0		С
F9	VCCAUX	-		
A8	PT8A	0		Т
B8	PT7D	0		С
C8	PT7C	0		Т
VCC	VCC	-		
A7	PT7B	0		С
B7	PT7A	0		Т
A6	PT6A	0		Т
B6	PT6B	0		С
D8	PT6C	0		Т
F8	PT6D	0		С
C7	PT6E	0		Т
E8	PT6F	0		С
D7	PT5D	0		С
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E7	PT5C	0		Т
A5	PT5B	0		С
C6	PT5A	0		Т
B5	PT4A	0		Т
A4	PT4B	0		С
D6	PT4C	0		Т
F7	PT4D	0		С
B4	PT4E	0		Т
GND	GND	-		
C5	PT4F	0		С
F6	PT3D	0		С
E5	PT3C	0		Т
E6	PT3B	0		С
D5	PT3A	0		Т
A3	PT2D	0		С
C4	PT2C	0		Т
A2	PT2B	0		С
B2	PT2A	0		Т
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E14	GND	-		



Lead-Free Packaging

Commercial

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256C-3TN100C	256	1.8V/2.5V/3.3V	78	-3	Lead-Free TQFP	100	COM
LCMXO256C-4TN100C	256	1.8V/2.5V/3.3V	78	-4	Lead-Free TQFP	100	COM
LCMXO256C-5TN100C	256	1.8V/2.5V/3.3V	78	-5	Lead-Free TQFP	100	COM
LCMXO256C-3MN100C	256	1.8V/2.5V/3.3V	78	-3	Lead-Free csBGA	100	COM
LCMXO256C-4MN100C	256	1.8V/2.5V/3.3V	78	-4	Lead-Free csBGA	100	COM
LCMXO256C-5MN100C	256	1.8V/2.5V/3.3V	78	-5	Lead-Free csBGA	100	COM

Part Number	LUTs	Supply Voltage	l/Os	Grade	Package	Pins	Temp.
LCMXO640C-3TN100C	640	1.8V/2.5V/3.3V	74	-3	Lead-Free TQFP	100	COM
LCMXO640C-4TN100C	640	1.8V/2.5V/3.3V	74	-4	Lead-Free TQFP	100	COM
LCMXO640C-5TN100C	640	1.8V/2.5V/3.3V	74	-5	Lead-Free TQFP	100	COM
LCMXO640C-3MN100C	640	1.8V/2.5V/3.3V	74	-3	Lead-Free csBGA	100	COM
LCMXO640C-4MN100C	640	1.8V/2.5V/3.3V	74	-4	Lead-Free csBGA	100	COM
LCMXO640C-5MN100C	640	1.8V/2.5V/3.3V	74	-5	Lead-Free csBGA	100	COM
LCMXO640C-3TN144C	640	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	COM
LCMXO640C-4TN144C	640	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	COM
LCMXO640C-5TN144C	640	1.8V/2.5V/3.3V	113	-5	Lead-Free TQFP	144	COM
LCMXO640C-3MN132C	640	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	COM
LCMXO640C-4MN132C	640	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	COM
LCMXO640C-5MN132C	640	1.8V/2.5V/3.3V	101	-5	Lead-Free csBGA	132	COM
LCMXO640C-3BN256C	640	1.8V/2.5V/3.3V	159	-3	Lead-Free caBGA	256	COM
LCMXO640C-4BN256C	640	1.8V/2.5V/3.3V	159	-4	Lead-Free caBGA	256	COM
LCMXO640C-5BN256C	640	1.8V/2.5V/3.3V	159	-5	Lead-Free caBGA	256	COM
LCMXO640C-3FTN256C	640	1.8V/2.5V/3.3V	159	-3	Lead-Free ftBGA	256	COM
LCMXO640C-4FTN256C	640	1.8V/2.5V/3.3V	159	-4	Lead-Free ftBGA	256	COM
LCMXO640C-5FTN256C	640	1.8V/2.5V/3.3V	159	-5	Lead-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	l/Os	Grade	Package	Pins	Temp.
LCMXO1200C-3TN100C	1200	1.8V/2.5V/3.3V	73	-3	Lead-Free TQFP	100	COM
LCMXO1200C-4TN100C	1200	1.8V/2.5V/3.3V	73	-4	Lead-Free TQFP	100	COM
LCMXO1200C-5TN100C	1200	1.8V/2.5V/3.3V	73	-5	Lead-Free TQFP	100	COM
LCMXO1200C-3TN144C	1200	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	COM
LCMXO1200C-4TN144C	1200	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	COM
LCMXO1200C-5TN144C	1200	1.8V/2.5V/3.3V	113	-5	Lead-Free TQFP	144	COM
LCMXO1200C-3MN132C	1200	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	COM
LCMXO1200C-4MN132C	1200	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	COM
LCMXO1200C-5MN132C	1200	1.8V/2.5V/3.3V	101	-5	Lead-Free csBGA	132	COM
LCMXO1200C-3BN256C	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free caBGA	256	COM
LCMXO1200C-4BN256C	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free caBGA	256	COM
LCMXO1200C-5BN256C	1200	1.8V/2.5V/3.3V	211	-5	Lead-Free caBGA	256	COM
LCMXO1200C-3FTN256C	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free ftBGA	256	COM
LCMXO1200C-4FTN256C	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free ftBGA	256	COM
LCMXO1200C-5FTN256C	1200	1.8V/2.5V/3.3V	211	-5	Lead-Free ftBGA	256	COM